

ANGI027035-P47

S-band matched GaN Device

Features:

Frequency: 2.7~3.5GHz Saturated Output Power: $P_{sat} \ge 47dBm$ PowerGain: Gain $\ge 11dB$ Add-Efficiency: PAE $\ge 48\%$ Port Matching: $Z_{in}/Z_{out} = 50\Omega$

Description:

ANGI027035-P47 is an internal matching GaN device, which adopts advanced co-planar internal matching MCM and thin film circuit technology. The typical working frequency range is 2.7~3.5GHz. This device can be used in different RF/Microwave system and subsystem.

The high output power level, high efficiency and wide operating temperature range can make application very flexible.

Maximun Ratings (TC=25°C, Not recommended working under this condition):

	Symbol	Value	Unit
Voltage between source and drain	Vds	40	V
Voltage between gate and source	V _{GS}	-5	V
Storage Temperature Range	Tstg	-65 to +175	°C
Drain and Source Channel Temperature	Tch	175	°C

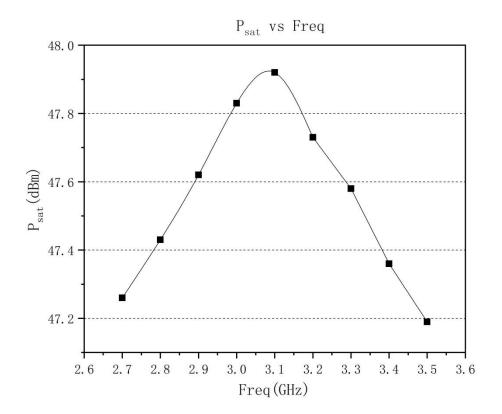
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Electrical Characteristics:

			Value			
	Symbol	Test condition	Min	Тур	Max	Unit
Drain Current	ldsr	Vds=28V CW. Pin: 36dBm Freq: 2.7~3.5GHz	-	3.2	-	А
Saturated Output Power	Psat		47	-	-	dBm
Gain	Gp		11	-	-	dB
Add-Efficiency	PAE		48	-	-	%
Gain Flatness	ΔG		-0.8	-	+0.8	dB

Typical Curve:

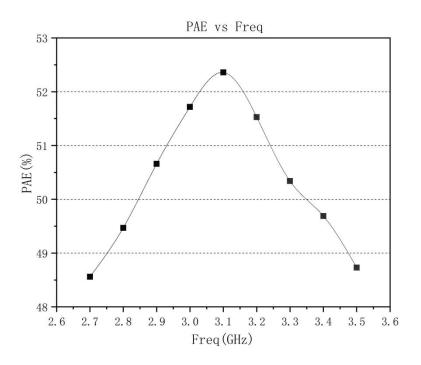


If you need more detailed product information, please contact our marketing personnel or designers. Contact: Peter.Zhang Email: peter.zhang@anserrf.com

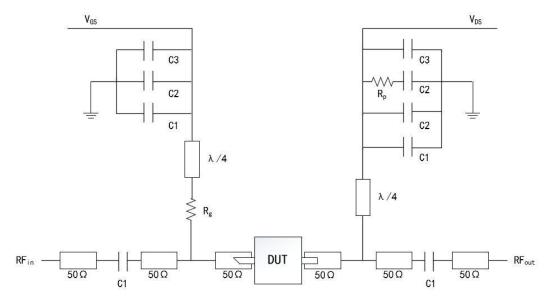
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AnserRF

Internal Matching GaN Device



Application Circuit:



DUT: Device to be tested

C1:8pF	R _p :51Ω
C2:1000pF	R _G :15Ω

C3:100uF

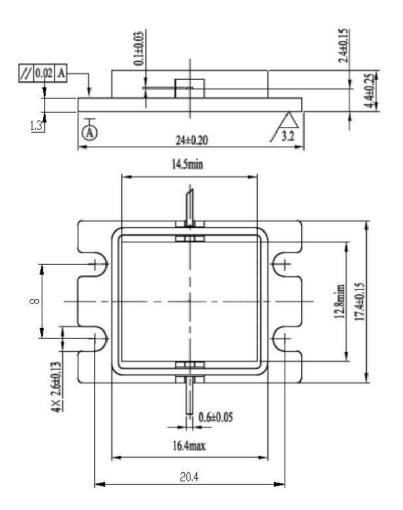
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ESD Level:



Outline:



Precautions for use:

- Pay attention to drying transportation and storage.
- Pay attention to anti-static during chip use and assembly, and wear grounding anti-static bracelet.
- When powering up, first apply grid power then add leakage.

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